Requirements on the sample production of the adaptors.

适配器生产须知：

|  |  |  |
| --- | --- | --- |
| 1 | FR4-Standard, TG 140C, Halogen-free： | 标准FR4板材，TG温度140，无卤素 |
| 2 | **Copper 35micros thick** Tin spraying or gold plating for other non-GFZ area. No plating of gold or tin for the Wire adaptors（Drawing sTGC\_WireXXXX） | 铜皮厚度35微米，表面裸露铜皮镀金,镀金厚度>30u"和镀镍厚度50u". 特别需要镀金的地方是GFZ插座区域，如果两次镀金，两次镀金的重叠区域应该避开GFZ区域 (下图GFZ插座区域) |
| 2.1 | For drawing sTGC\_StripXXXX and sTGC\_PadXXX: 1. Gold plating GFZ coppers feet （See drawing below）, >=100u" of nickel, >=30u’’ gold with hardness 120-200 knoop per ASTM B 488, type 2.
2. If gold plating in two steps, the overlap should avoid GFZ area
3. No special requirement on other exposed copper: gold or tin plating or not to plate anything.
 | 对于图纸sTGC\_StripXXXX and sTGC\_PadXXX：1. 表面裸露的GFZ插座触点（看下图）镀镍金, 镀镍厚度>100u", 镀金厚度>30u’’并且硬度120-200 knoop per ASTM B 488, type 2.
2. 如果分段镀金，两次镀金不得在GFZ区域重叠
3. 其他裸露的铜区域，无特别的镀金或者镀锡要求，可以使用一般技术镀金或者锡，也可以不镀。
 |
| 2.2 | For drawing sTGC\_WireXXXX: No special requirement on gold or tin plating or not to plate anything. | 对于图纸sTGC\_WireXXXX: 无特别的镀金或者镀锡要求，可以镀金或者锡，也可以不镀。 |
| 3 | outer surface with solder mask in green color ( LPI ), thickness ≥10μm  | 外表面除了焊点和触点，其他区域涂绿色阻焊油墨, 厚度：≥10μm |
| 4 | IPC 2 standard test after production | IPC2级检测，检测断线和短路等 |
| 5 | white silkscreens | 印刷白色标示符号 |
| 6 | di-electric layer between neighbour copper pattern, thickness precision 10%, the impedance between signal line and ground is 65+/- 10% Ω. A plenty of signal lines are connected out through the GFZ feet, if the thickness of the di-electric or distance between lines need to be adjusted, the impedance of above should maintained. | **两层线路之间的绝缘层的厚度公差10%**，每一个信号线和地之间的输入阻抗65+/- 10% Ω。信号线的均通过下图的GFZ引脚引出，数量众多，因此无论调整绝缘层厚度还是线距都需要保证每一条信号线和地之间的阻抗满足上述数值。 |
| 7 | precision of thickness of board10%, signal line width precision 20%, other requirement which is not declared will follow IPC-A-600H（2）and IPC-6012C 2 | 板总厚度公差+/-10%；线宽公差：+/-20%；其它未说明的按IPC-A-600H（2级）和IPC-6012C 2级标准管控。 |
| 8 | The size precision of the board±0.25mm | 外形公差按±0.25mm控制 |



The quantity to produced are as below.

2016-07-14 样品加工数量

|  |  |  |
| --- | --- | --- |
|  | adaptor ID | planed to produce for samples |
| 1 | sTGC\_Strip\_AB\_406Ch\_Left | 8 |
| 2 | sTGC\_Strip\_AB\_406Ch\_Right | 8 |
| 3 | sTGC\_Strip\_AB\_365Ch | 8 |
| 5 | sTGC\_Strip\_AB\_307Ch | 8 |
| 29 | sTGC\_Pad\_AB\_075L | 26 |
| 30 | sTGC\_Pad\_AB\_075R | 27 |

待定样品加工数量。

|  |  |  |
| --- | --- | --- |
|  | adaptor ID | planed to produce for samples |
| 6 | sTGC\_WireA\_AB\_GS3P1 | 40 |
| 9 | sTGC\_WireA\_AB\_GS3P2 | 40 |
| 12 | sTGC\_WireA\_AB\_GS3P3 | 40 |
| 15 | sTGC\_WireA\_AB\_GS3P4 | 40 |
| 22 | sTGC\_WireA\_AB\_GS2P1 | 45 |
| 23 | sTGC\_WireA\_AB\_GS2P2 | 45 |
| 24 | sTGC\_WireA\_AB\_GS2P3 | 45 |
| 24 | sTGC\_WireA\_AB\_GS2P4 | 45 |